

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

TSSOP Exp. Pad

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TOTAL MASS (g) : 0.054533

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002541	1000000	46595.8046875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.014625	975000	268187.1875		
		Iron (Fe)	7439-89-6	0.000360	24000	6601.53076172		
		Phosphorus (P)	7723-14-0	0.000004	300	73.3503417969		
		Zinc (Zn)	7440-66-6	0.000010	700	183.375839233		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
Lead Frame Total:				0.014999	1000000	275045.46875		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002064	1000000	37845.2148438		
		External Plating Total:				0.002064	1000000	37845.2148438
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001037	1000000	19016.0761719		
Internal Plating Total:				0.001037	1000000	19016.0761719		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000805	750000	14761.7558594		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000268	250000	4914.47265625		
Die Attach Total:				0.001073	1000000	19676.2285156		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.004875	150000	89395.734375		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.026650	820000	488696.65625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000813	25000	14908.4570312		
		Carbon Black (C)	1333-86-4	0.000163	5000	2989.02636719		
		Encapsulation Total:				0.032501	1000000	595989.875
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000318	1000000	5831.35205078		
					TOTAL MASS (g) :	0.054533		